TOSHIBA 2SJ507

TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE (L2-\pi-MOS V)

2 S J 5 0 7

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

4V Gate Drive

Low Drain-Source On Resistance : $RDS(ON) = 0.5\Omega$ (Typ.)

High Forward Transfer Admittance : $|Y_{fs}| = 1.0S$ (Typ.)

Low Leakage Current : $I_{DSS} = -100 \mu A \text{ (Max.)} \text{ (V}_{DS} = -60 \text{ V)}$

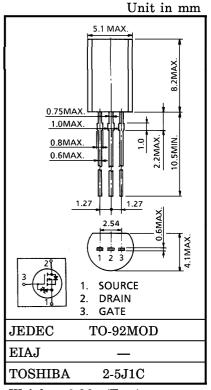
Enhancement-Mode : $V_{th} = -0.8 \sim -2.0V$

 $(V_{DS} = -10V, I_D = -1mA)$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC			UNIT					
Drain-Source Voltage			V					
Drain-Gate Voltage (R _{GS} =20kΩ)			V					
Gate-Source Voltage			V					
DC	$I_{\mathbf{D}}$	-1	Α					
Pulse	I_{DP}	-3	A					
Drain Power Dissipation (Ta=25°C)			W					
Single Pulse Avalanche Energy**			mJ					
Avalanche Current			Α					
Repetitive Avalanche Energy*			mJ					
Channel Temperature			°C					
Storage Temperature Range			°C					
	DC Pulse on (Ta=25°C) e Energy**	$\begin{array}{c c} & V_{DSS} \\ \hline GS = 20 k\Omega) & V_{DGR} \\ \hline & V_{GSS} \\ \hline DC & I_{D} \\ \hline Pulse & I_{DP} \\ pon (Ta = 25 ^{\circ}C) & P_{D} \\ \hline E Energy ** & E_{AS} \\ \hline I_{AR} \\ \hline Energy * & E_{AR} \\ \hline T_{ch} \\ \hline \end{array}$	$\begin{array}{c ccccc} & V_{DSS} & -60 \\ & V_{DGR} & -60 \\ & V_{GSS} & \pm 20 \\ \hline DC & I_{D} & -1 \\ Pulse & I_{DP} & -3 \\ Pon & (Ta=25^{\circ}C) & P_{D} & 0.9 \\ E & Energy^{**} & E_{AS} & 249.6 \\ & I_{AR} & -1 \\ Energy^{*} & E_{AR} & 0.09 \\ & T_{ch} & 150 \\ \hline \end{array}$					

INDUSTRIAL APPLICATIONS



Weight: 0.36g (Typ.)

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	138	°C/W

Note;

Repetitive rating; Pulse Width Limited by Max. junction temperature.

 $V_{DD} = -25V$, Starting $T_{ch} = 25^{\circ}C$, L = 339mH, $R_{G} = 25\Omega$, $I_{AR} = -1A$

This transistor is an electrostatic sensitive device. Please handle with caution.

TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

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CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakag	e Current	IGSS	$V_{GS} = \pm 16V, V_{DS} = 0V$		_	±10	μ A
Drain Cut-of	f Current	$I_{ m DSS}$	$V_{DS} = -60V, V_{GS} = 0V$	_	_	-100	μ A
Drain-Source Voltage	Breakdown		$I_D = -10 \text{mA}, V_{GS} = 0 \text{V}$	-60	_	_	V
Gate Thresh	old Voltage	$V_{ m th}$	$V_{DS} = -10V, I_{D} = -1mA$	-0.8	_	-2.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = -4V, I_D = -0.5A$ $V_{GS} = -10V, I_D = -0.5A$	_	0.72	1.0	Ω
Forward Tra Admittance	nsfer	Y _{fs}	$V_{DS} = -10V, I_{D} = -0.5A$	0.5	1.0	_	s
Input Capaci	tance	C_{iss}		_	170	_	
Reverse Transfer Capacitance			V_{DS} = -10V, V_{GS} =0V, f =1MHz	_	25	_	pF
Output Capacitance		C_{oss}		_	72	_	i
Switching Time	Rise Time		V_{GS} V	_	20	_	
	Turn-on Time	t _{on}		_	35	_	ns
	Fall Time	tf			30	_	115
	Turn-off Time	t _{off}	$V_{\mathrm{IN}}: \mathrm{t_r}, \mathrm{t_f} < 5\mathrm{ns}, V_{\mathrm{DD}} = -30\mathrm{V}$ $\mathrm{Duty} \leq 1\%, \mathrm{t_w} = 10\mu\mathrm{s}$	_	135	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = -48V, V_{GS} = -10V,$	_	5.6	_	C
Gate-Source Charge		$ m Q_{gs}$	$I_{D} = -1A$	_	3.9	_	nC
Gate-Drain ("Miller") Charge		\mathbf{Q}_{gd}		_	1.7		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I_{DR}	_	_	_	-1	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	-3	A
Diode Forward Voltage	$V_{ m DSF}$	$I_{DR} = -1A$, $V_{GS} = 0V$	_	_	1.5	V
Reverse Recovery Time		$I_{DR} = -1A$, $V_{GS} = 0V$	_	58		ns
Reverse Recovery Charge	$Q_{\mathbf{rr}}$	$\mathrm{dI_{DR}}$ / dt = 50A / $\mu\mathrm{s}$		72.5	_	nC

MARKING

